Product Change Notification

Change Notification #: **115190 - 03**

Change Title:

Intel® Omni-Path Director Class Switch 100 Series 24 Slot Base 1MM 100SWD24B1N

Intel® Omni-Path Director Class Switch 100 Series 6 Slot Base 1MM 100SWD06B1N

Intel® Omni-Path Director Class Switch 100 Series 24 Slot FRU Chassis 100SWD24CHS

Intel® Omni-Path Director Class Switch 100 Series 6 Slot FRU Chassis 100SWD06CHS

Intel® Omni-Path Director Switch Management Module 100 Series 100SWDMGTSH

PCN 115190-03, Product Design, Documentation, Label, Product Material,

Regulatory Update, Content Update, and Firmware Update

Reason for Revision: Added TUV GS mark to Regulatory Labels and Firmware Update

Date of Publication: **March 1, 2017**

Key Characteristics of the Change:

Product Design, Documentation, Label, Product Material

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material:	March 03, 2017

The date of "First Availability of Post-Conversion Material" is the projected date that a customer may expect to receive the Post-Conversion Materials. This date is determined by the projected depletion of inventory at the time of the PCN publication. The depletion of inventory may be impacted by fluctuating supply and demand, therefore, although customers should be prepared to receive the Post-Converted Materials on this date, Intel will continue to ship and customers may continue to receive the pre-converted materials until the inventory has been depleted.

Description of Change to the Customer:

Reason for Revision: Added TUV GS mark to Regulatory Labels and Firmware Update

The Omni-Path Director Switch products listed in the table below shall be modified to update their Regulatory labels, update the packaging labels, update their Read Me First documents, add content, and update their firmware to version 10.3.

Affected Product Code	Product Description
100SWD06B1N	Intel® Omni-Path Director Class Switch 100 Series 6 Slot Base 1MM 100SWD06B1N
100SWD24B1N	Intel® Omni-Path Director Class Switch 100 Series 24 Slot Base 1MM 100SWD24B1N
100SWD06CHS	Intel® Omni-Path Director Class Switch 100 Series 6 Slot FRU Chassis 100SWD06CHS
100SWD24CHS	Intel® Omni-Path Director Class Switch 100 Series 24 Slot FRU Chassis 100SWD24CHS
100SWDMGTSH	Intel® Omni-Path Director Switch Management Module 100 Series 100SWDMGTSH

Overview of Changes:

Change 1: Regulatory and Compliance Certifications were successfully acquired from Argentina, Korea, Eurasian Customs Union, Taiwan, Mexico, Vietnam, Serbia, and Ukraine. The changes include the following:

A. The regulatory label on the product will be updated with the marks for Argentina (IRAM/S), Korea (KC/MSIP), the Eurasian Customs Union (EAC), Taiwan (BSMI), Mexico (NOM), Vietnam (VNTA), Serbia, **TUV GS** and Ukraine.

B. The packaging labels will be updated:
   i. Add Korean Label Requirements.
   ii. Update CE Mark with Intel Address Lines.
   iii. Add a California Prop 65 warning.

C. The Read Me First document will be updated:
   i. Change EN 55022 to EN 55032.
   ii. Add contact for Intel CE mark related questions.

D. The Read Me First document will be included in Russian to meet EAC requirements.

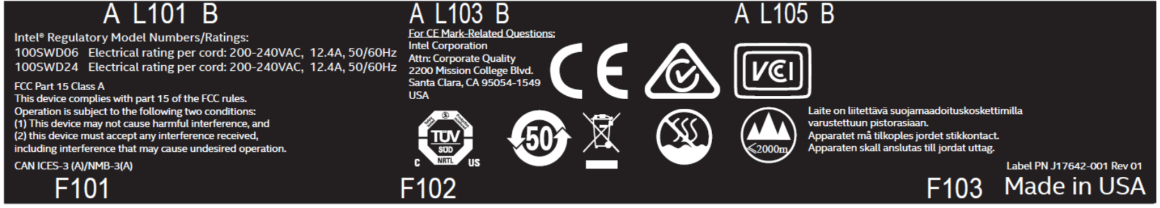
Change 2: A USB cable will be included with each MM identified in this PCN.

Change 3: Fan module connection grounding will be enhanced.

Change 4: 100SWD06B1N, 100SWD24B1N, and 100SWDMGTSH firmware shall be updated from 10.0 to 10.2.

Product Material Change Details:
Change 1A: Product Regulatory Label updates.

Before (100SWD06 & 100SWD24):



Intel® Regulatory Model Numbers/Ratings:
100SWD06   Electrical rating per cord: 200-240VAC, 12.4A, 50/60Hz
100SWD24   Electrical rating per cord: 200-240VAC, 12.4A, 50/60Hz

FCC Part 15 Class A
This device complies with part 15 of the FCC rules.
Operation is subject to the following two conditions:
(1) This device may not cause harmful interference, and
(2) this device must accept any interference received,
including interference that may cause undesired operation.

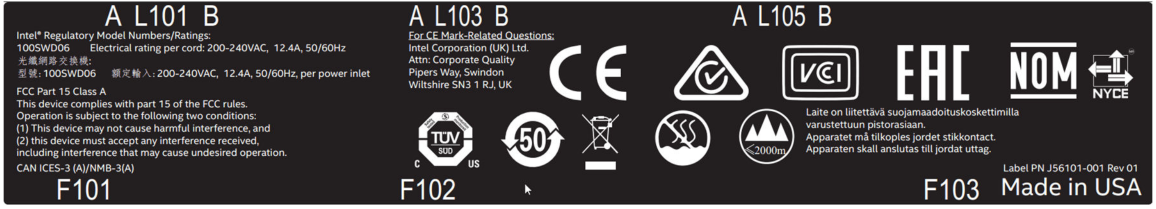
CAN ICES-3 (A)/NMB-3(A)

For CE Mark-Related Questions:
Intel Corporation
Attn: Corporate Quality
2200 Mission College Blvd.
Santa Clara, CA 95054-1549
USA

Laite on liitettävä suojamaadoituskoskettimilla
varustettuun pistorasiaan.
Apparatet må tilkoples jordet stikkontact.
Apparaten skall anslutas till jordat uttag.

Label PN J17642-001 Rev 01
Made in USA

After (100SWD06):



Intel® Regulatory Model Numbers/Ratings:
100SWD06   Electrical rating per cord: 200-240VAC, 12.4A, 50/60Hz
光纖網路交換機:
型號: 100SWD06   額定輸入: 200-240VAC, 12.4A, 50/60Hz, per power inlet

FCC Part 15 Class A
This device complies with part 15 of the FCC rules.
Operation is subject to the following two conditions:
(1) This device may not cause harmful interference, and
(2) this device must accept any interference received,
including interference that may cause undesired operation.

CAN ICES-3 (A)/NMB-3(A)

For CE Mark-Related Questions:
Intel Corporation (UK) Ltd.
Attn: Corporate Quality
Pipers Way, Swindon
Wiltshire SN3 1 RJ, UK

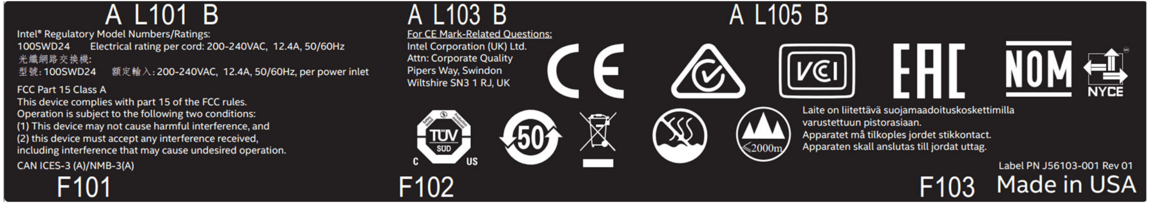
Laite on liitettävä suojamaadoituskoskettimilla
varustettuun pistorasiaan.
Apparatet må tilkoples jordet stikkontact.
Apparaten skall anslutas till jordat uttag.

Label PN J56101-001 Rev 01
Made in USA

警告使用者:
此為甲類資訊技術設備，於居住環境中使用時，
可能會造成射頻擾動，在此種情況下，使用者會
被要求採取某些適當的對策。

Label PN J56102-001 Rev 01

After (100SWD24):



Intel® Regulatory Model Numbers/Ratings:
100SWD24   Electrical rating per cord: 200-240VAC, 12.4A, 50/60Hz
光纖網路交換機:
型號: 100SWD24   額定輸入: 200-240VAC, 12.4A, 50/60Hz, per power inlet

FCC Part 15 Class A
This device complies with part 15 of the FCC rules.
Operation is subject to the following two conditions:
(1) This device may not cause harmful interference, and
(2) this device must accept any interference received,
including interference that may cause undesired operation.

CAN ICES-3 (A)/NMB-3(A)

For CE Mark-Related Questions:
Intel Corporation (UK) Ltd.
Attn: Corporate Quality
Pipers Way, Swindon
Wiltshire SN3 1 RJ, UK

Laite on liitettävä suojamaadoituskoskettimilla
varustettuun pistorasiaan.
Apparatet må tilkoples jordet stikkontact.
Apparaten skall anslutas till jordat uttag.

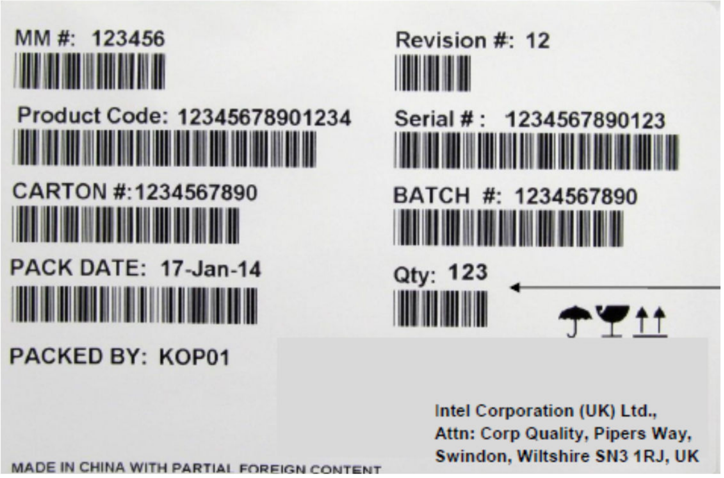
Label PN J56103-001 Rev 01
Made in USA

警告使用者:
此為甲類資訊技術設備，於居住環境中使用時，
可能會造成射頻擾動，在此種情況下，使用者會
被要求採取某些適當的對策。

Label PN J56104-001 Rev 01

Change 1B: i: Add KCC Certification Section, ii: Update CE Mark with Intel Address Lines, and iii: Add California Prop65 Warning Statement to Carton Label (to correct the omission on previous product packaging label)

Before (100SWD06 & 100SWD24):



MM #: 123456
Revision #: 12
Product Code: 12345678901234
Serial # : 1234567890123
CARTON #:1234567890
BATCH #: 1234567890
PACK DATE: 17-Jan-14
Qty: 123
PACKED BY: KOP01

Intel Corporation (UK) Ltd.,
Attn: Corp Quality, Pipers Way,
Swindon, Wiltshire SN3 1RJ, UK

MADE IN CHINA WITH PARTIAL FOREIGN CONTENT

After (100SWD06 & 100SWD24):

MM #:945677
MM Rev #:12
Product Code:100SWD24B1N
Serial #: 1234567890123
CARTON #:1234567890
BATCH #:USFU123456
PACK DATE:09-Dec-16
Qty: 1

PACKED BY: KOP1

WARNING
This product contains chemicals known to the State of California to cause cancer and birth defects or other reproductive harm.

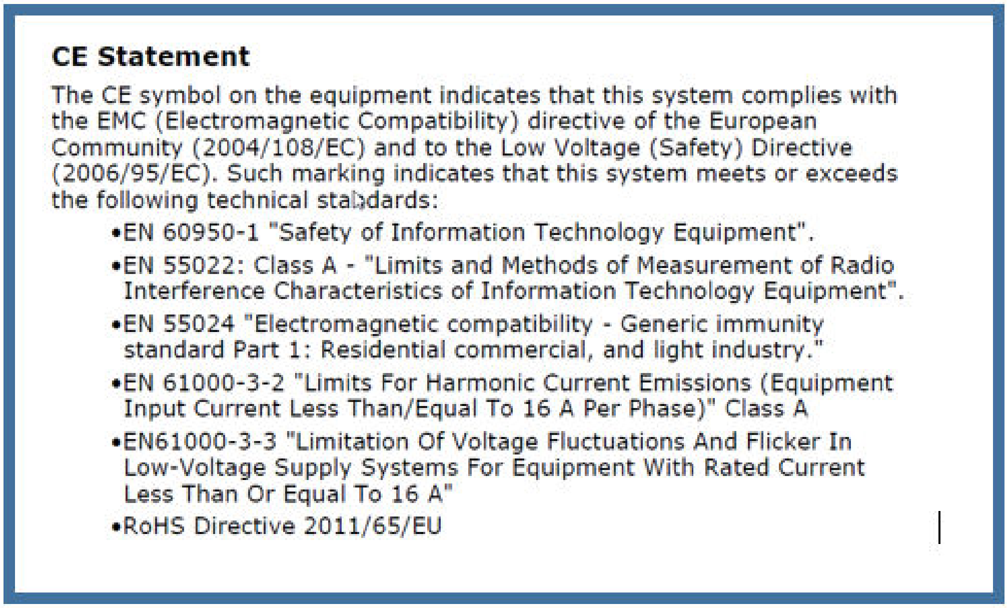
MSIP-REM-CPU-100SWD24
Intel Omni-Path Director Class Switch
Model: 100SWD24
Applicant: Intel Corporation
Manufacturer: Flextronics Internationl USA, Inc.

For CE mark related questions:
Intel Corporation (UK) Ltd.,
Attn: Corp Quality
Pipers Way
Swindon, Wiltshire SN3 1RJ, UK

MADE IN UNITED STATES WITH PARTIAL FOREIGN CONTENT

Change 1C: i: The Read Me First insert's CE statement will revise EN 55022 to EN 55032. EN55032 is replacing EN55022 and others for CE marking of multimedia equipment. ii: Intel's CE contact address will also be added to this section:

Before:

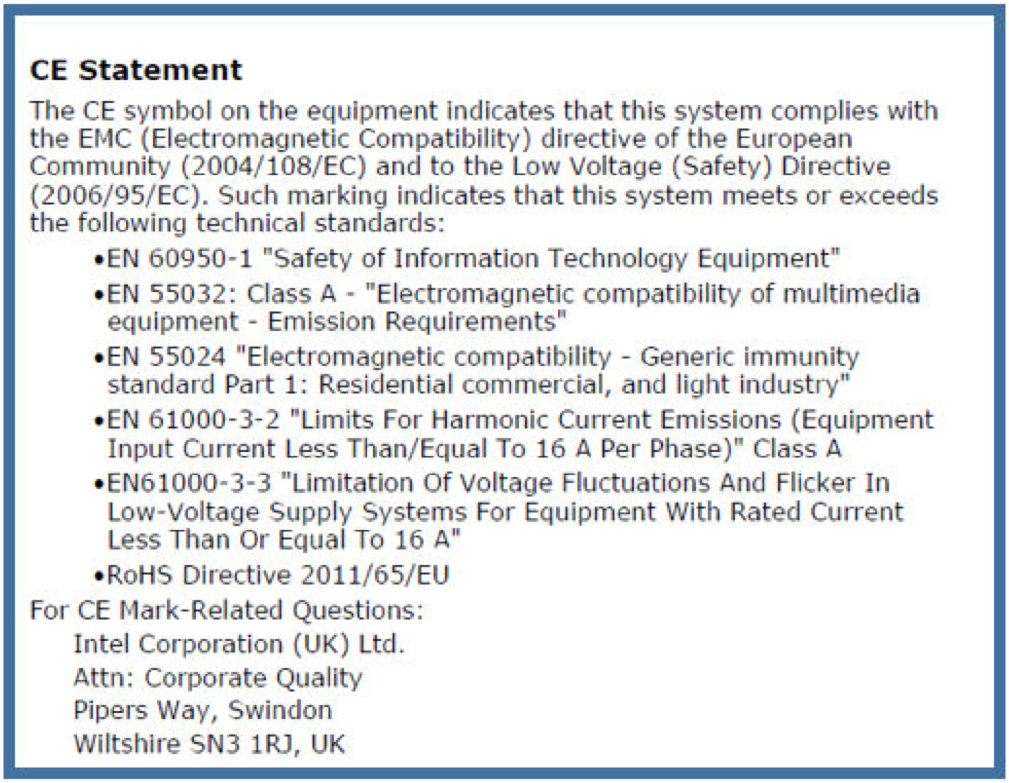


CE Statement

The CE symbol on the equipment indicates that this system complies with the EMC (Electromagnetic Compatibility) directive of the European Community (2004/108/EC) and to the Low Voltage (Safety) Directive (2006/95/EC). Such marking indicates that this system meets or exceeds the following technical standards:

- EN 60950-1 "Safety of Information Technology Equipment".
- EN 55022: Class A - "Limits and Methods of Measurement of Radio Interference Characteristics of Information Technology Equipment".
- EN 55024 "Electromagnetic compatibility - Generic immunity standard Part 1: Residential commercial, and light industry."
- EN 61000-3-2 "Limits For Harmonic Current Emissions (Equipment Input Current Less Than/Equal To 16 A Per Phase)" Class A
- EN61000-3-3 "Limitation Of Voltage Fluctuations And Flicker In Low-Voltage Supply Systems For Equipment With Rated Current Less Than Or Equal To 16 A"
- RoHS Directive 2011/65/EU

After:



CE Statement

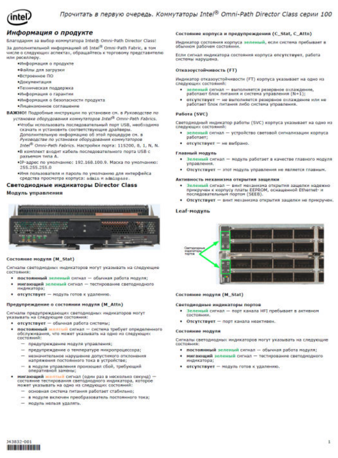
The CE symbol on the equipment indicates that this system complies with the EMC (Electromagnetic Compatibility) directive of the European Community (2004/108/EC) and to the Low Voltage (Safety) Directive (2006/95/EC). Such marking indicates that this system meets or exceeds the following technical standards:

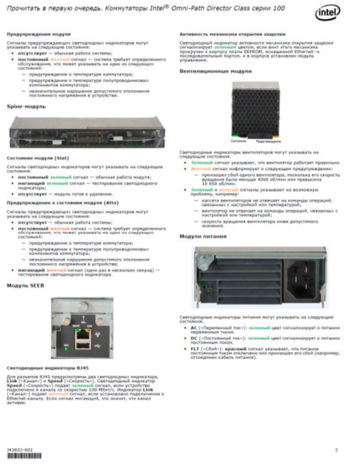
- EN 60950-1 "Safety of Information Technology Equipment"
- EN 55032: Class A - "Electromagnetic compatibility of multimedia equipment - Emission Requirements"
- EN 55024 "Electromagnetic compatibility - Generic immunity standard Part 1: Residential commercial, and light industry"
- EN 61000-3-2 "Limits For Harmonic Current Emissions (Equipment Input Current Less Than/Equal To 16 A Per Phase)" Class A
- EN61000-3-3 "Limitation Of Voltage Fluctuations And Flicker In Low-Voltage Supply Systems For Equipment With Rated Current Less Than Or Equal To 16 A"
- RoHS Directive 2011/65/EU

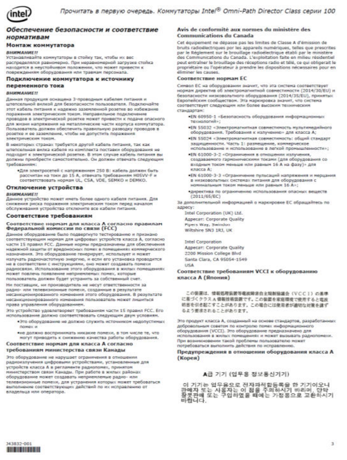
For CE Mark-Related Questions:

Intel Corporation (UK) Ltd.
Attn: Corporate Quality
Pipers Way, Swindon
Wiltshire SN3 1RJ, UK

Change 1D: The Read Me First document will be included in Russian to meet EAC requirements.







Change 2: The Chassis and Management Module will now come with a 2M USB Type A Male to Type A Male Cable

Change 3: The Fan module connector grounding will be enhanced through additional contact to chassis ground. This will minimize ground noise improving the I2C signal guardband and eliminate the scarce occurrence of a logged I2C error.

Change 4: 100SWD06B1N, 100SWD24B1N, and 100SWDMGTSH firmware shall be changed from 10.0.1.2.1 to 10.2.0.0.152/154.

Customer Impact of Change and Recommended Action:

Intel is not recommending additional qualification of these changes by customers.
There is no change to the switch Intel Material Master (MM) numbers.
Please contact your local Intel Field Sales Representative if you have any questions about this change.

Milestone dates are estimates and subject to change based on business and operational conditions.

* Other names and brands may be claimed as the property of others.

Products Affected / Intel Ordering Codes:

Product Code	MM#	Pre Change MM# Rev	Post Change MM# Rev	Pre Change TA	Post Change TA	Pre Change AS	Post Change AS
100SWD06B1N	945676	11	13 ++	J12783-011	J12783-012	J11517-011	J11517-012
100SWD24B1N	945677	11	13 ++	J12778-011	J12778-012	H89346-013	H89346-014
100SWD06CHS	947192	04	06 ++	J18616-004	J18616-005	J19700-003	J19700-004
100SWD24CHS	947193	04	06 ++	J18618-004	J18618-005	J18617-003	J18617-004
100SWDMGTSH	945776	04	05	H87892-006	H87892-006	H60416-007	H60416-008

++ The MM# Rev incremented once with the changes described in PCN Revisions 00 thru 01 and once for PCN Revision 02.

PCN Revision History:

Date of Revision:	Revision Number:	Reason:
December 21, 2016	00	Originally Published PCN
December 22, 2016	01	Revised images
January 10, 2017	02	Added FRU Chassis MMs
March 1, 2017	03	Added TUV GS mark to Regulatory Labels and Firmware Update

Product Change Notification
115190 - 03

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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